

N-Channel ENHANCEMENT MODE POWER MOSFET

 **Pb** Lead(Pb)-Free

FEATURES:

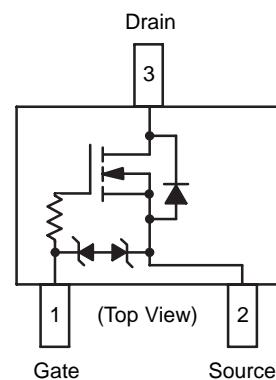
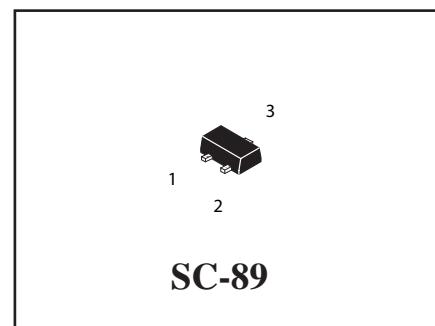
- * Power Mosfet : 1.8V Rated
- * Gate-Source ESD Protected: 2000 V
- * High-Side Switching
- * Low On-Resistance: 0.7Ω
- * Low Threshold: 0.8 V (typ)
- * Fast Switching Speed: 10 ns

BENEFITS:

- * Ease in Driving Switches
- * Low Offset (Error) Voltage
- * Low-Voltage Operation
- * High-Speed Circuits
- * Low Battery Voltage Operation

APPLICATIONS:

- * Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- * Battery Operated Systems
- * Power Supply Converter Circuits
- * Load/Power Switching Cell Phones, Pagers



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	5 secs	Steady State	Unit
Drain-Source Voltage	V_{DS}	20	± 6	V
Gate-Source Voltage	V_{GS}			
Continuous Drain Current ($T_J = 150^\circ C$) ^b	I_D	600	500	mA
		400	350	
Pulsed Drain Current ^a	I_{DM}	1000		mA
Continuous Source Current (diode conduction) ^b	I_S	275	250	
Maximum Power Dissipation ^b for SC-75	P_D	175	150	mW
		90	80	
Maximum Power Dissipation ^b for SC-89		275	250	
		160	140	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	−55 to 150		°C
Gate-Source ESD Rating (HBM, Method 3015)	ESD	2000		V

Notes

- d. Pulse width limited by maximum junction temperature.
- e. Surface Mounted on FR4 Board.

Device Marking

WTX1012 = A

Electrical Characteristics ($T_A=25^\circ\text{C}$ Unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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Static

Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	0.45		0.9	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$		± 0.5	± 1.0	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$		0.3	100	nA
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 85^\circ\text{C}$			5	μA
On-State Drain Current ¹	$I_{D(\text{on})}$	$V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	700			mA
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = 4.5 \text{ V}, I_D = 600 \text{ mA}$		0.41	0.70	Ω
		$V_{GS} = 2.5 \text{ V}, I_D = 500 \text{ mA}$		0.53	0.85	
		$V_{GS} = 1.8 \text{ V}, I_D = 350 \text{ mA}$		0.70	1.25	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 10 \text{ V}, I_D = 400 \text{ mA}$		1.0		S
Diode Forward Voltage ^a	V_{SD}	$I_S = 150 \text{ mA}, V_{GS} = 0 \text{ V}$		0.8	1.2	V

Dynamic

Total Gate Charge	Q_g	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 250 \text{ mA}$		750		pC
Gate-Source Charge	Q_{gs}			75		
Gate-Drain Charge	Q_{gd}			225		
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = 10 \text{ V}, R_L = 47 \Omega$ $I_D \approx 200 \text{ mA}, V_{GEN} = 4.5 \text{ V}, R_G = 10 \Omega$		5		ns
Rise Time	t_r			5		
Turn-Off Delay Time	$t_{d(\text{off})}$			25		
Fall Time	t_f			11		

Notes

1. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
2. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Characteristics Curve

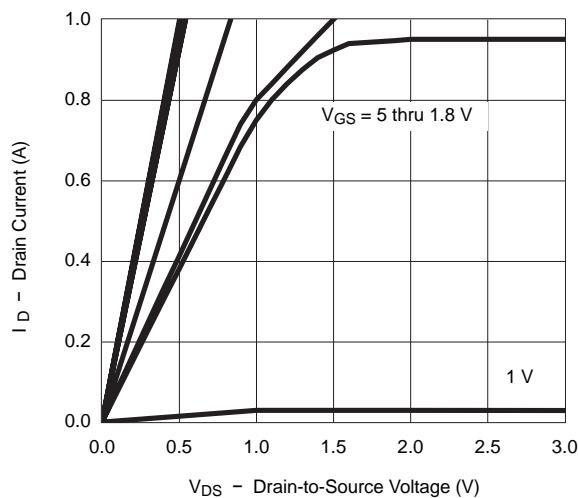


Fig.1 Output Characteristics

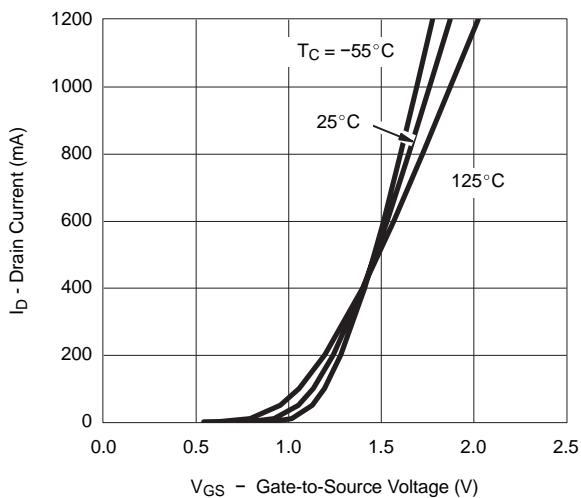


Fig.2 Transfer Characteristics

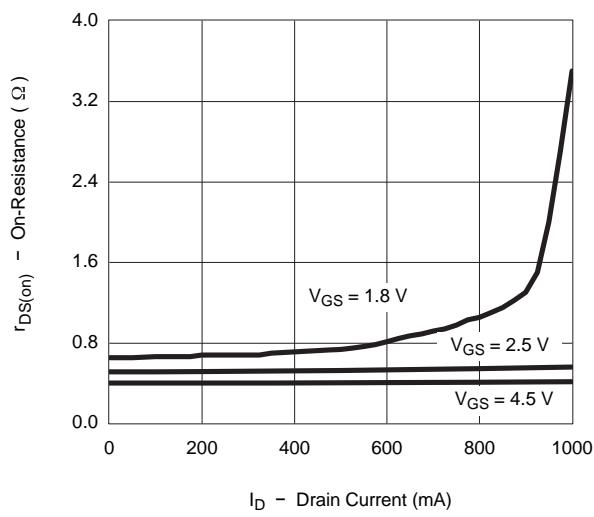


Fig.3 On-Resistance vs. Drain Current

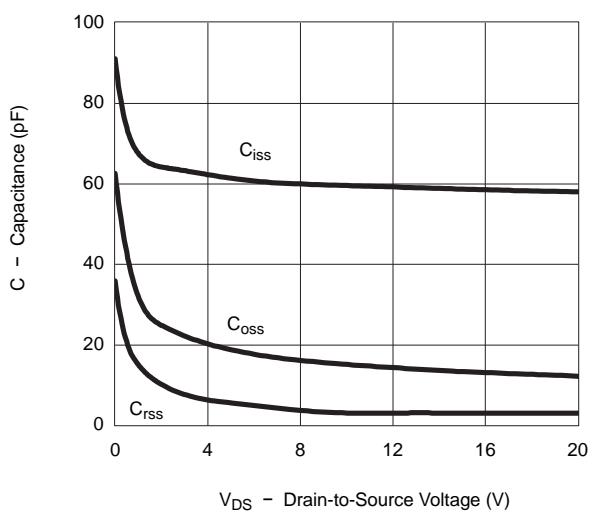


Fig.4 Capacitance

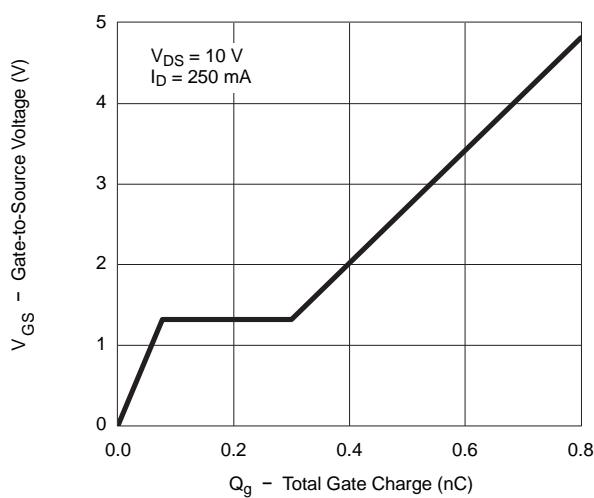


Fig.5 Gate Charge

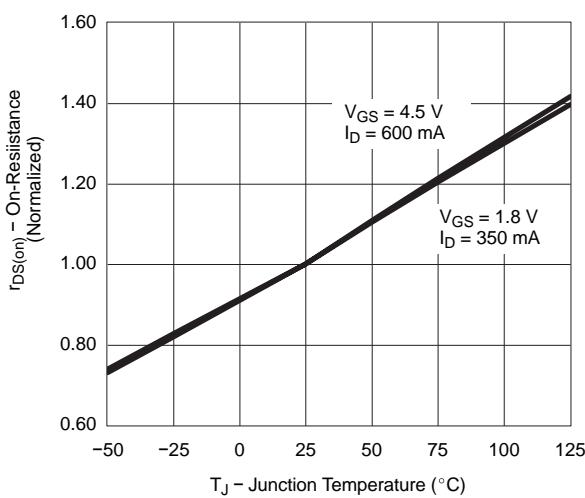


Fig.6 On-Resistance vs. Junction Temperature

Characteristics Curve

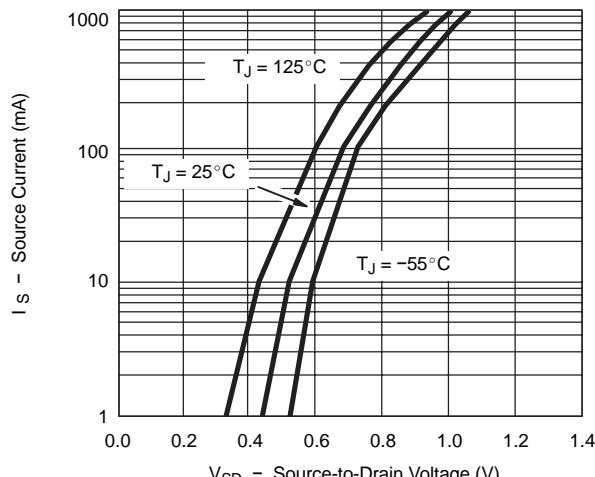


Fig.7 Source-Drain Diode Forward Voltage

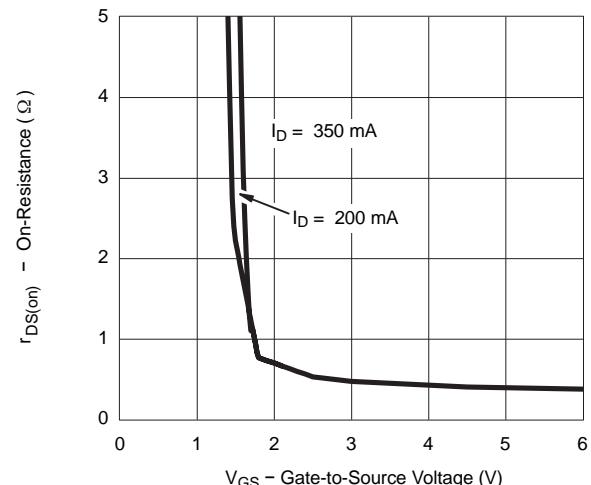


Fig.8 On-Resistance vs. Gate-to-Source Voltage

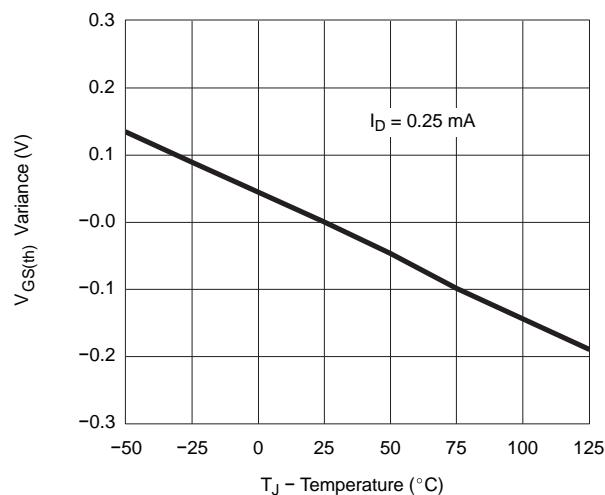


Fig.9 Threshold Voltage Variance vs. Temperature

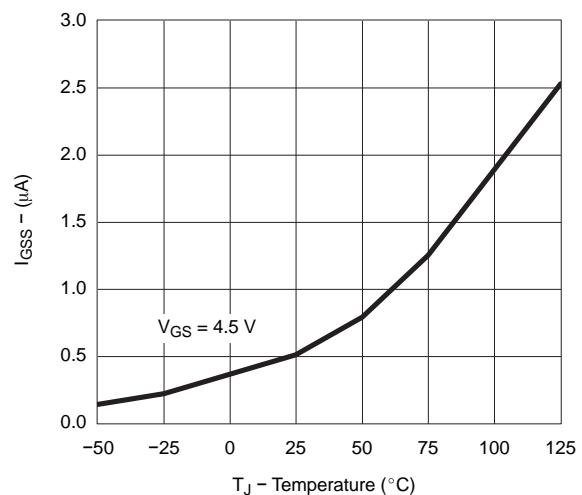


Fig.10 I_{GSS} vs. Temperature

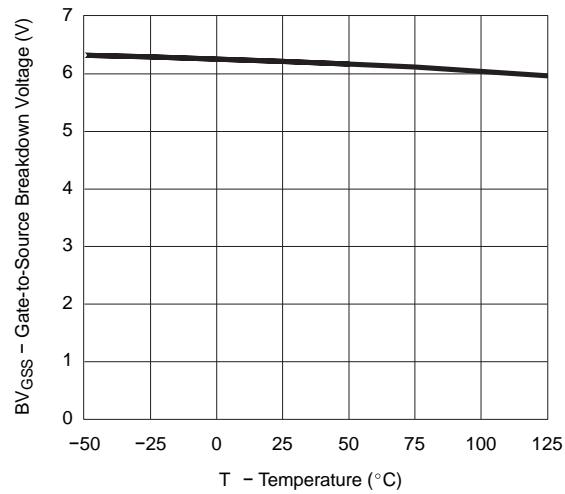


Fig.11 BV_{GSS} vs. Temperature

Characteristic Curves

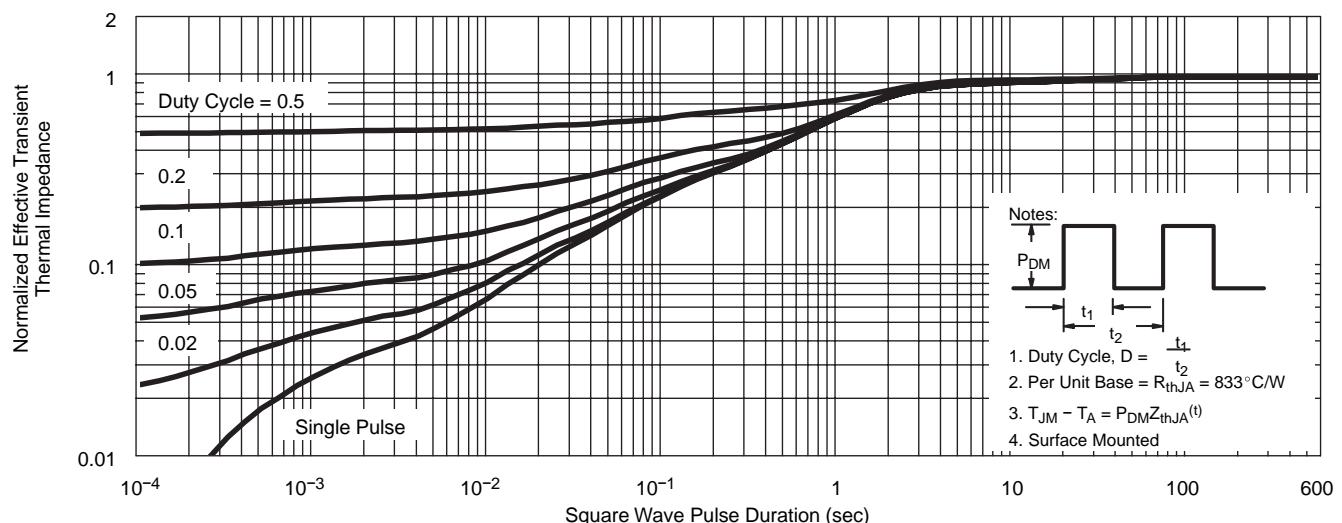


Fig.12 Normalized Thermal Transient Impedance, Junction-to-Ambient (SC-75A)

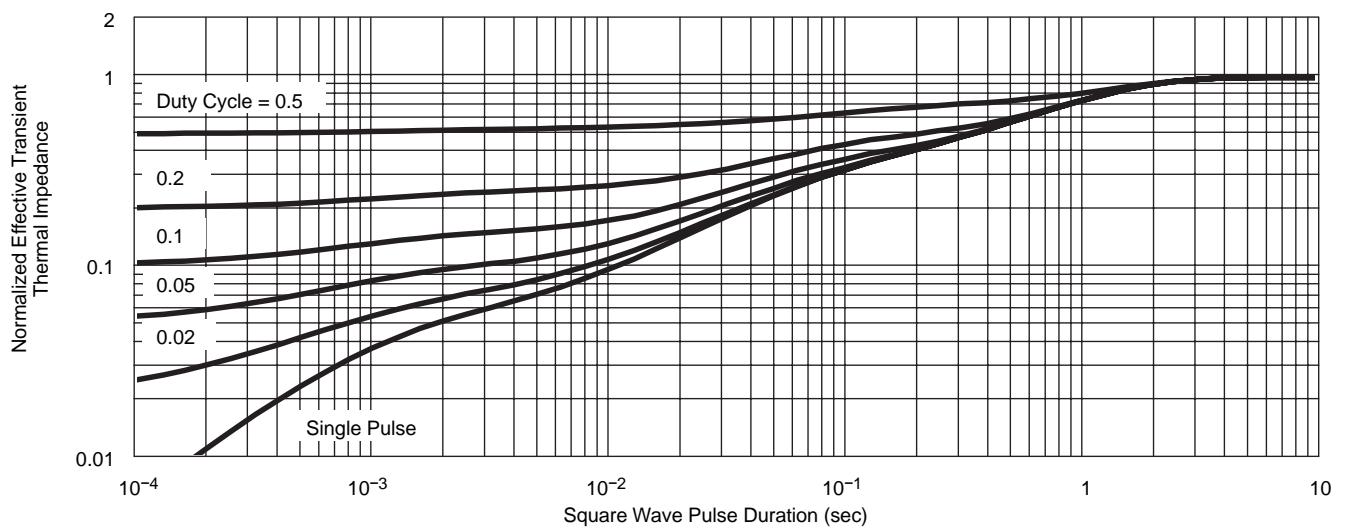
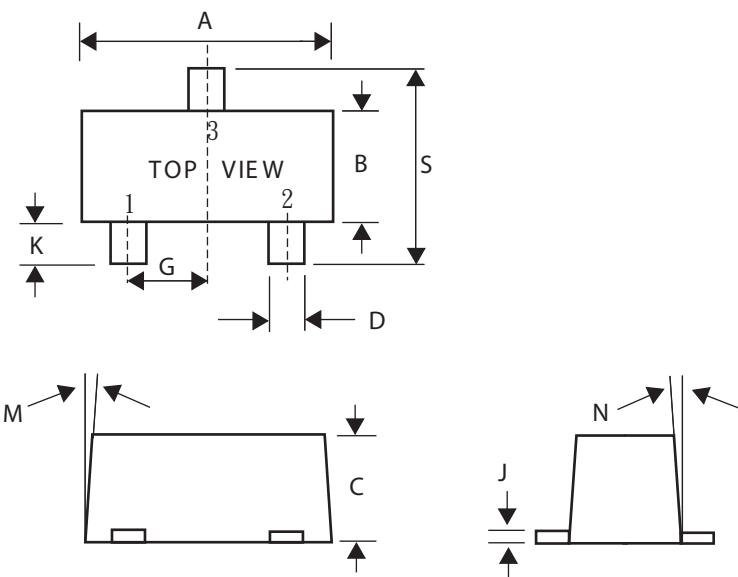


Fig.13 Normalized Thermal Transient Impedance, Junction-to-Foot

SC-89 Outline Demensions

Unit:mm



SC-89			
Dim	Min	Nom	Max
A	1.50	1.60	1.70
B	0.75	0.85	0.95
C	0.60	0.70	0.80
D	0.23	0.28	0.33
G	0.50BSC		
J	0.10	0.15	0.20
K	0.30	0.40	0.50
M	---	---	10°
N	---	---	10°
S	1.50	1.60	1.70